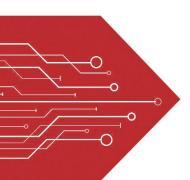
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- 1. BASE
- 2. COLLECTOR
- 3. EMITTER

PNP Transistors

■ Features

- Collector Current Capability Ic=-4A
- Collector Emitter Voltage VcEo=-140V
- Very low saturation voltages

Absolute Maximum Ratings Ta = 25°C

Parameter	Symbol	Rating	Unit	
Collector - Base Voltage	Vсво	-180		
Collector - Emitter Voltage	VCEO	-140	V	
Emitter - Base Voltage	Vево	-6		
Collector Current - Continuous	Ic	-4	^	
Peak Pulse Current	Ісм	-10	Α	
Collector Power Dissipation	Pc	3	W	
Thermal Resistance, Junction to Ambient (Note 1)	Reja	78	°C/W	
Operating and Storage Temperature Range	TJ,Tstg	-55 to 150	$^{\circ}$	

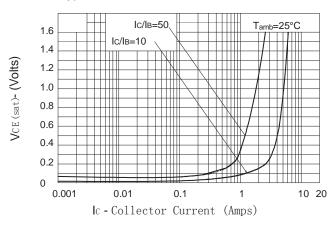
Note 1:For a device mounted with the collector lead on 25mm x 25mm 1oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still airconditions whilst operating in steady-state.

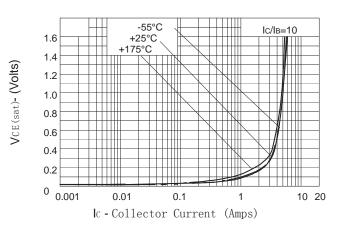
Electrical Characteristics Ta = 25°C

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit	
Collector- base breakdown voltage	VCBO Ic= -100 μA, IE=0		-180				
Collector- emitter breakdown voltage	VCER	Ic=-1 μA, Rв ≤ 1kΩ	-180			V	
Collector- emitter breakdown voltage	VCEO	Ic= -10 mA, IB=0	-140				
Emitter - base breakdown voltage	VEBO	IE= -100 μA, IC=0	-6				
Collector-base cut-off current	Ісво	Vcb= -150 V , IE=0			-50	nA	
Collector-base cut-on current		Vcb= -150 V , IE=0 , Ta = 100° C			-1	μΑ	
Collector cut-off current R < $1k\Omega$	ICER	VCE= -150 V , IE=0			-50	nA	
	ICER	Vce= -150 V , Ie=0 , Ta = 100° C			-1	μΑ	
Emitter cut-off current	ІЕВО	VEB= -6V , IC=0			-10	nA	
Collector-emitter saturation voltage		Ic=-100 mA, IB=-5 mA			-60	mV	
	VCE(sat)	Ic=-500 mA, Iв=-50mA			-120		
		Ic=-1 A, IB=-100mA			-150		
		Ic=-3 A, IB=-300mA			-370		
Base - emitter saturation voltage	VBE(sat)	Ic=-3 A, IB=-300mA			-1110		
Base - emitter turn-on voltage	VBE(on)	VCE= -5V, IC= -3A			-950		
DC current gain	hFE	VCE= -5V, IC= -10mA	100				
		Vce=- 5V, Ic= -1 A	100		300		
		VCE= -5V, IC= -3 A	75				
		VCE= -5V, IC= -10 A		10			
Switching Times	ton	Ic=-1A, I _{B1} =-100mA		68		ns	
	toff	IB2=100mA, Vcc=-50V		1030			
Collector output capacitance	Cob	Vcb= -20V,f=1MHz		40		pF	
Transition frequency	f⊤	VcE= -10V, Ic= -100mA,f=50MHz		110		MHz	

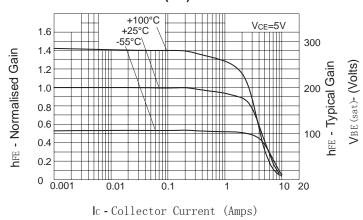


Typical Characterisitics

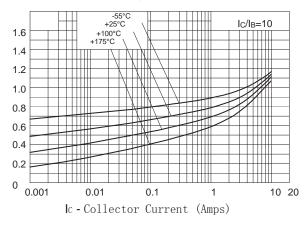




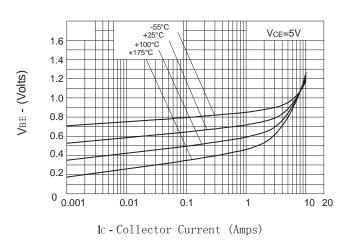
VCE(sat) v IC



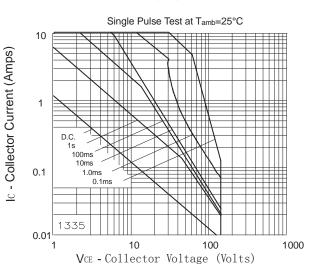
VCE(sat) v IC



hFE v IC



VBE(sat) v IC

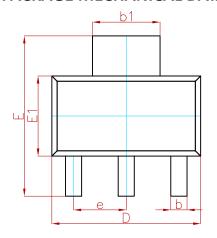


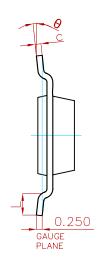
VBE(on) v IC

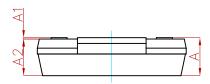
Safe Operating Area



PACKAGE MECHANICAL DATA

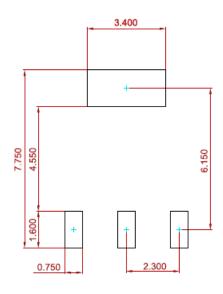






Symbol Dimensions In Millin		n Millimeters	neters Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
Α		1.800		0.071	
A1	0.020	0.100	0.001	0.004	
A2	1.500	1.700	0.059	0.067	
b	0.660	0.840	0.026	0.033	
b1	2.900	3.100	0.114	0.122	
С	0.230	0.350	0.009	0.014	
D	6.300	6.700	0.248	0.264	
E	6.700	7.300	0.264	0.287	
E1	3.300	3.700	0.130	0.146	
е	2.300(BSC)		0.091(BSC)		
L	0.750		0.030		
θ	0°	10°	0°	10°	

Suggested Pad Layout



Note:

- 1.Controlling dimension:in millimeters.
- 2.General tolerance:±0.050mm.
- 3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
FZT955-MS	SOT-223	1000



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